



ABSTRACT

[Abstract of the Disclosure]

A protection tape removing apparatus used in a semiconductor packaging process and a method of assembling a semiconductor package are disclosed. In the method and apparatus, after a wafer to which a protection tape is adhered is sawed to be divided into individual chips and then a frame for manufacturing a semiconductor package is attached to the individual chips, the protection tape is individually removed from the individual chips. The wafer can be divided into the individual chips without any damage caused to the chips by performing a die attaching process in a state where the protection tape is not removed.

[Representative Drawing]

FIG. 12

[Index Term]

15 Division of chips, Protection tape, Individual chip, Pressure pin, Pressure roller